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U.S. UTILITY Patent Application

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Yoshihisa Furuta Yoshinori Watanabe

**APPLICANTS** 

Semiconductor chip resin-sealing method and adhesive tape for pasting lead frames or the like

PTO-2040 12/99

ISSUING CLASSIFICATION							
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TERMINAL	DRAWINGS	CLAIMS ALLOWED.
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not extend beyond the expiration data of U.S Patent. No.		ISSUE FEE
	Primary Examiner) (Data)	Amount Due Date Paid
The terminal months of this patent have been disclaimed:		ISSUE BATCH NUMBER
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